

IN THE SPECIFICATION:

On page 6, please amend the paragraph beginning at line 14 as follows:

--Metallic surfaces 16 can be provided on the bottom 4 of recess 2, on which heat producing sender elements can be installed. They are used to remove the heat and pass through the wall of the circuit board 1 to one of its free surfaces, as shown in Fig. [[6]] 7. To shorten this feedthrough, a sink can be installed on the bottom 4 of recess 2 in which the metallic surfaces 16 are located and the heat producing elements are installed. The metallic surface 17 provided on the corresponding free surface of the circuit board 1 conducts the heat away. An additional cooling device can also be installed there. The surfaces 16 and 17 and their heat-conducting connection can be realized with a number of feedthrough contacts 18 as indicated in Fig. 7. However metal blocks can also be installed in the wall of circuit board 1.--